

20V N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} max	I _D max T _A = +25°C
	$25m\Omega$ @ $V_{GS} = 4.5V$	6.5A
20V	31mΩ @ V _{GS} = 2.5V	5.9A
	60mΩ @ V _{GS} = 1.8V	4.5A

Description

This MOSFET is designed to minimize the on-state resistance (RDS(ON)) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

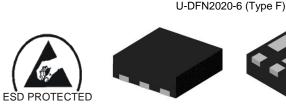
- Battery Management Application
- Power Management Functions
- DC-DC Converters

Features

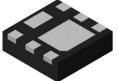
- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm²
- Low Gate Threshold Voltage
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please contact us or your local Diodes representative. https://www.diodes.com/quality/product-definitions/

Mechanical Data

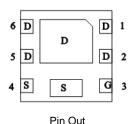
- Case: U-DFN2020-6
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish NiPdAu over Copper Leadframe. Solderable per MIL-STD-202, Method 208 ⁽⁴⁾
- Weight: 0.0065 grams (Approximate)



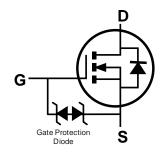




Bottom View



Pin Out Bottom View



Internal Schematic

Ordering Information (Note 4)

Part Number	Reel Size (inches)	Quantity Per Reel
DMN2025UFDF-7	7	3,000
DMN2025UFDF-13	13	10,000

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.



Marking Information

Site 1



5F = Product Type Marking Code YM = Date Code Marking Y = Year (ex: H = 2020) M = Month (ex: 9 = September)

Date Code Key

Date Code Ney												
Year	2017		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	E		Н	ı	J	K	L	М	N	0	Р	R
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Site 2



5F = Product Type Marking Code YWX = Date Code Marking Y = Year (ex: 0 = 2020)

W = Week (ex: a = week 27; z represents week 52 and 53)

X = Internal Code (ex: U = Monday)

Date Code Key			_									
Year	2017		2020	2021	2022	2023	2024	2025	2026	2027	2028	2029
Code	7		0	1	2	3	4	5	6	7	8	9
Week	1-26			27-52				53				
Code		P	N-Z			a	-Z			Z	_	
Internal Code	Sun	1	Mon		Tue	W	ed	Thu		Fri		Sat
Code	Т		U		V	V	V	Х		Υ		Z



Maximum Ratings (@ $T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Drain-Source Voltage	VDSS	20	V		
Gate-Source Voltage	V_{GSS}	±10	V		
Continuous Drain Current (Note 6) Vgs = 4.5V	lο	6.5 5.2	А		
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%	o)		I _{DM}	30	A
Continuous Source-Drain Diode Current	Is	2	Α		
Avalanche Current (Note 7) L = 0.1mH	las	8	Α		
Avalanche Energy (Note 7) L = 0.1mH			Eas	8	mJ

Thermal Characteristics

Characteristic		Symbol	Value	Unit
Total Power Dissipation (Note 5)	T _A = +25°C	PD	0.7	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	$R_{\theta JA}$	170	°C/W
Total Power Dissipation (Note 6)	T _A = +25°C	PD	1.6	W
Thermal Resistance, Junction to Ambient (Note 6)	R _{0JA}	76	°C/W	
Thermal Resistance, Junction to Case (Note 6)	Rejc	15	C/VV	
Operating and Storage Temperature Range		TJ, TSTG	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)	-			•		
Drain-Source Breakdown Voltage	BVDSS	20	_	_	V	$V_{GS} = 0V, I_{D} = 250\mu A$
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	_	_	1	μΑ	$V_{DS} = 20V, V_{GS} = 0V$
Gate-Source Leakage	Igss	_	_	±10	μΑ	$V_{GS} = \pm 10V$, $V_{DS} = 0V$
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	Vgs(TH)	0.5		1.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
			14.5	25		$V_{GS} = 4.5V, I_D = 4A$
Static Drain-Source On-Resistance	R _{DS(ON)}	_	21	31	mΩ	$V_{GS} = 2.5V, I_D = 4A$
			41.5	60		VGS = 1.8V, ID = 4A
Diode Forward Voltage	VsD	_	0.7	1.2	V	V _G S = 0V, I _S = 5A
DYNAMIC CHARACTERISTICS (Note 9)						
Input Capacitance	Ciss	_	486	_		V _{DS} = 10V, V _{GS} = 0V, f = 1.0MHz
Output Capacitance	Coss	_	92	_	pF	
Reverse Transfer Capacitance	Crss	_	77	_		
Gate Resistance	Rg	_	3.2	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	5.9	_		
Total Gate Charge (V _{GS} = 10V)	Qg	_	12.3	_	nC	V 40V I 6.5A
Gate-Source Charge	Qgs	_	0.8	_	nc	$V_{DS} = 10V, I_{D} = 6.5A$
Gate-Drain Charge	Q _{gd}	_	2.2	_		
Turn-On Delay Time	t _{D(ON)}	_	3.4	_		
Turn-On Rise Time	t _R	_	5.4	_		$V_{DS} = 10V, V_{GS} = 4.5V,$
Turn-Off Delay Time	tD(OFF)	_	17.6	_	ns	$R_G = 6\Omega$, $R_L = 10\Omega$, $I_D = 1A$
Turn-Off Fall Time	tF	_	9.3	_		
Reverse Recovery Time	trr	_	7.7	_	ns	IF = 1A, di/dt = 100A/µs
Reverse Recovery Charge	Q _{RR}	—-	1.5	_	nC	I _F = 1A, di/dt = 100A/μs

5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

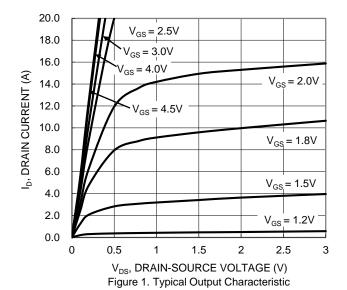
^{6.} Device mounted on FR-4 substrate PC board, 2oz copper, with 1inch square copper plate.

7. IAS and EAS ratings are based on low frequency and duty cycles to keep T_J = +25°C.

^{8.} Short duration pulse test used to minimize self-heating effect.

^{9.} Guaranteed by design. Not subject to product testing.





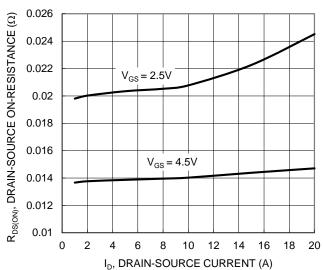


Figure 3. Typical On-Resistance vs. Drain Current and Gate Voltage

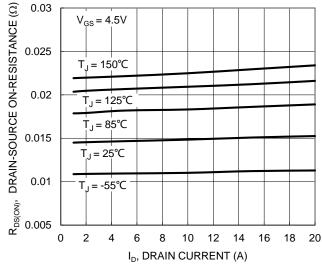
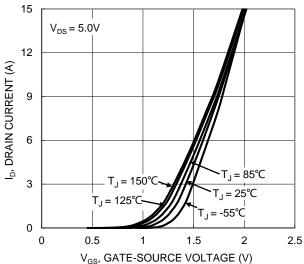


Figure 5. Typical On-Resistance vs. Drain Current and Junction Temperature



V_{GS}, GATE-SOURCE VOLTAGE (V) Figure 2. Typical Transfer Characteristic

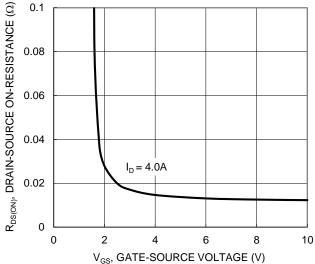


Figure 4. Typical Transfer Characteristic

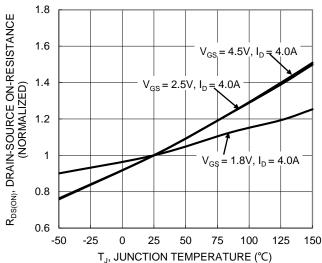


Figure 6. On-Resistance Variation with Junction Temperature



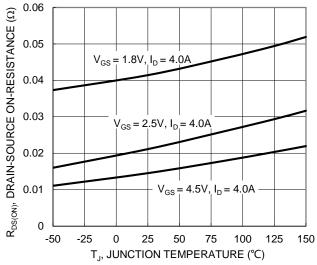


Figure 7. On-Resistance Variation with Junction Temperature

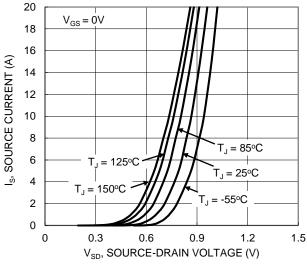


Figure 9. Diode Forward Voltage vs. Current

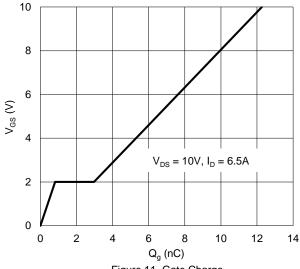


Figure 11. Gate Charge

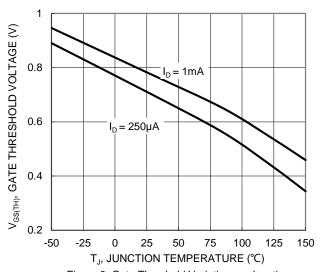


Figure 8. Gate Threshold Variation vs. Junction Temperature

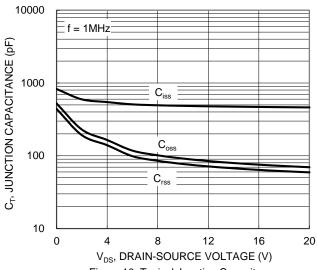
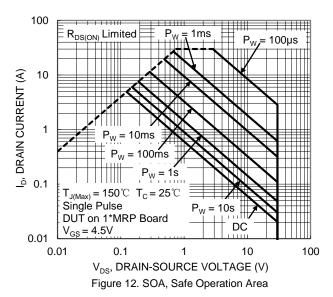


Figure 10. Typical Junction Capacitance





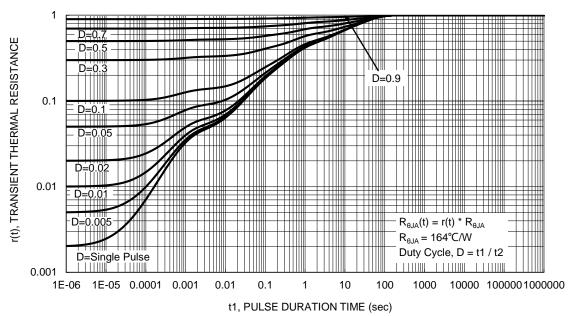


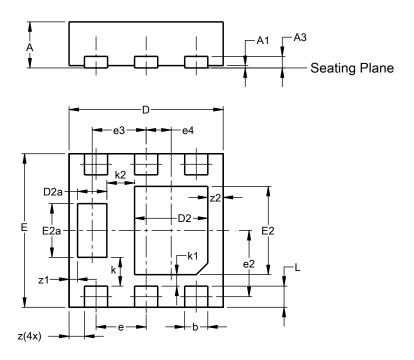
Figure 13. Transient Thermal Resistance



Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)

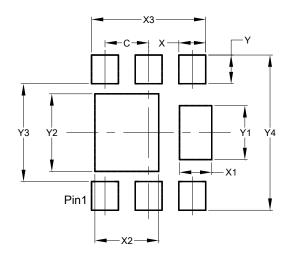


U-DFN2020-6										
Dim	(Type F) Dim Min Max Typ									
Α	0.57									
A1	0.00 0.05 0.03									
A3	0.15									
b	0.25	0.25 0.35 0.30								
D	1.95	2.05	2.00							
D2	0.85									
D2a	0.33	0.33 0.43 0.38								
Е	1.95 2.05 2.0									
E2	1.05	1.25	1.15							
E2a	0.65	0.75	0.70							
е		0.65 BS	С							
e2	().863 BS	SC							
е3		0.70 BS	C							
e4	().325 BS	Ö							
k		0.37 BS	O							
k1		0.15 BS	O							
k2	0.36 BSC									
L	0.225	0.325	0.275							
Z		0.20 BS	С							
z1	0.110 BSC									
z2		0.20 BS	С							
All C	imens	ions in	mm							

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (Type F)



Dimensions	Value (in mm)			
С	0.650			
X	0.400			
X1	0.480			
X2	0.950			
Х3	1.700			
Y	0.425			
Y1	0.800			
Y2	1.150			
Y3	1.450			
Y4	2.300			



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